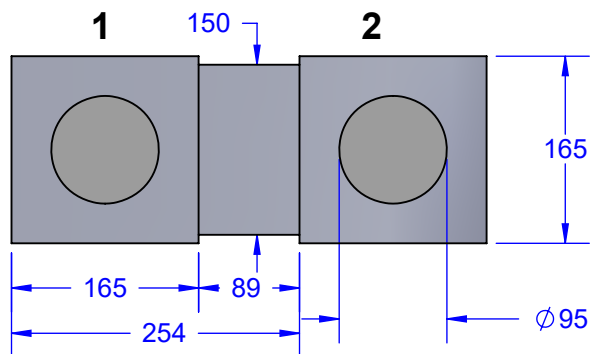
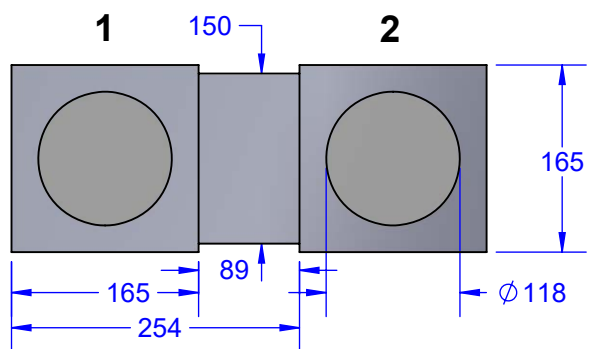


WIRE BONDING PAD

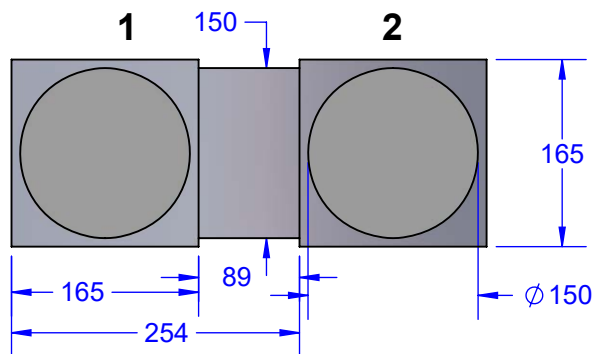
DETAIL 1



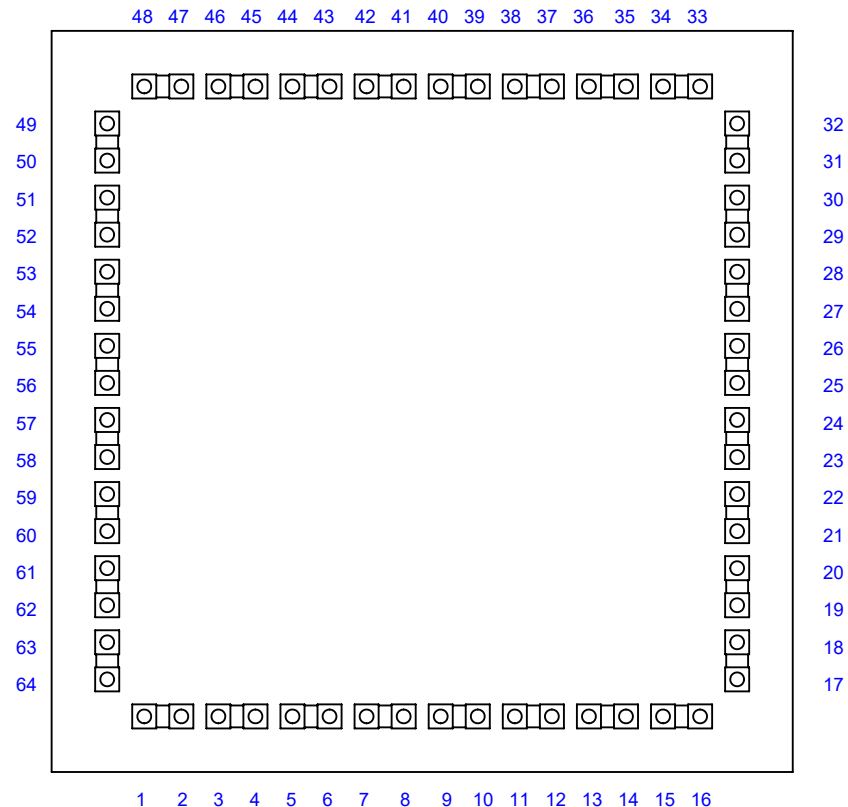
DETAIL 2



DETAIL 3



DAISY CHAIN PATTERN PAD VIEW



NOTES:

- 1) DIMENSIONS: MICRONS (μm) OR AS SPECIFIED.
- 2) THICKNESS: 635 μm (OTHER AVAILABLE).
- 3) PASSIVATION: NITRIDE 8KA THICKNESS (.8 μm).
- 4) PACKAGING: STANDARD WAFFLE PACK (TRAY).
- 5) PAD METAL THICKNESS: 9KA (.9 μm).

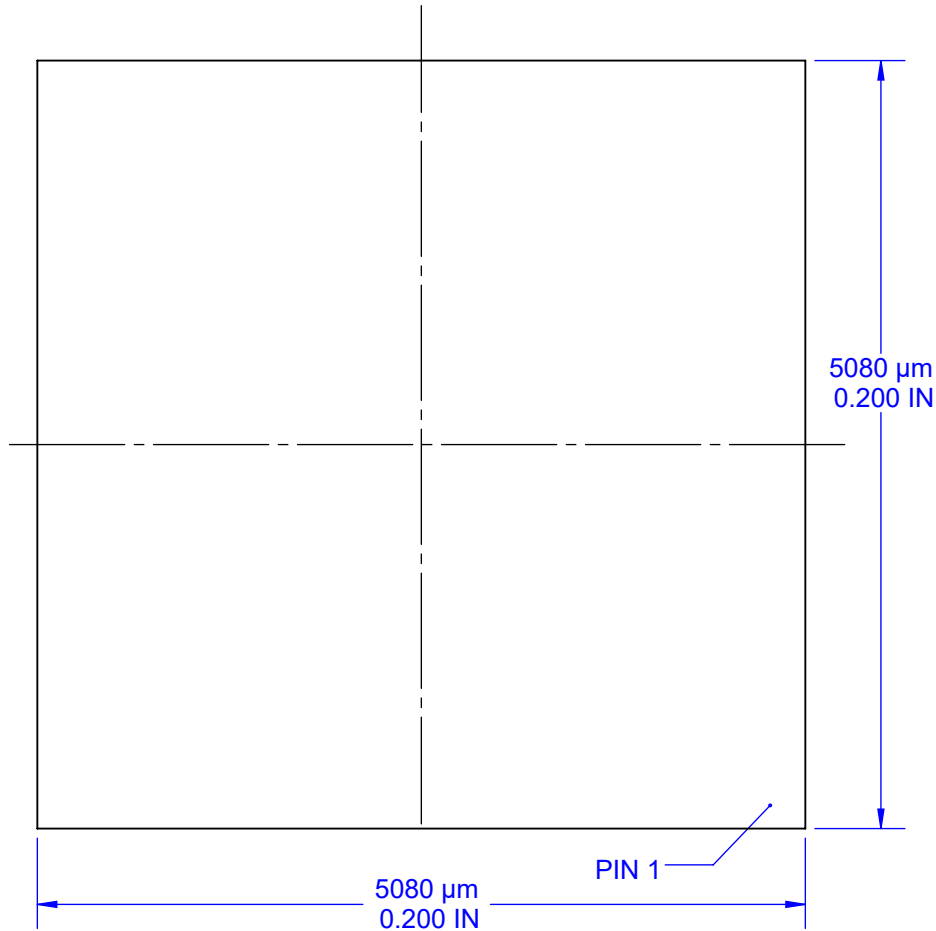
PART NUMBER TABLE

PART NUMBER	DIE SIZE	DIE PER WAFER	BOND SITE	DETAIL
FCN64K5A254-DC	5.08mm	340	$\varnothing 95\mu\text{m}$	1
FCN64N5A254-DC	5.08mm	340	$\varnothing 118\mu\text{m}$	2
FCN64U5A254-DC	5.08mm	340	$\varnothing 150\mu\text{m}$	3

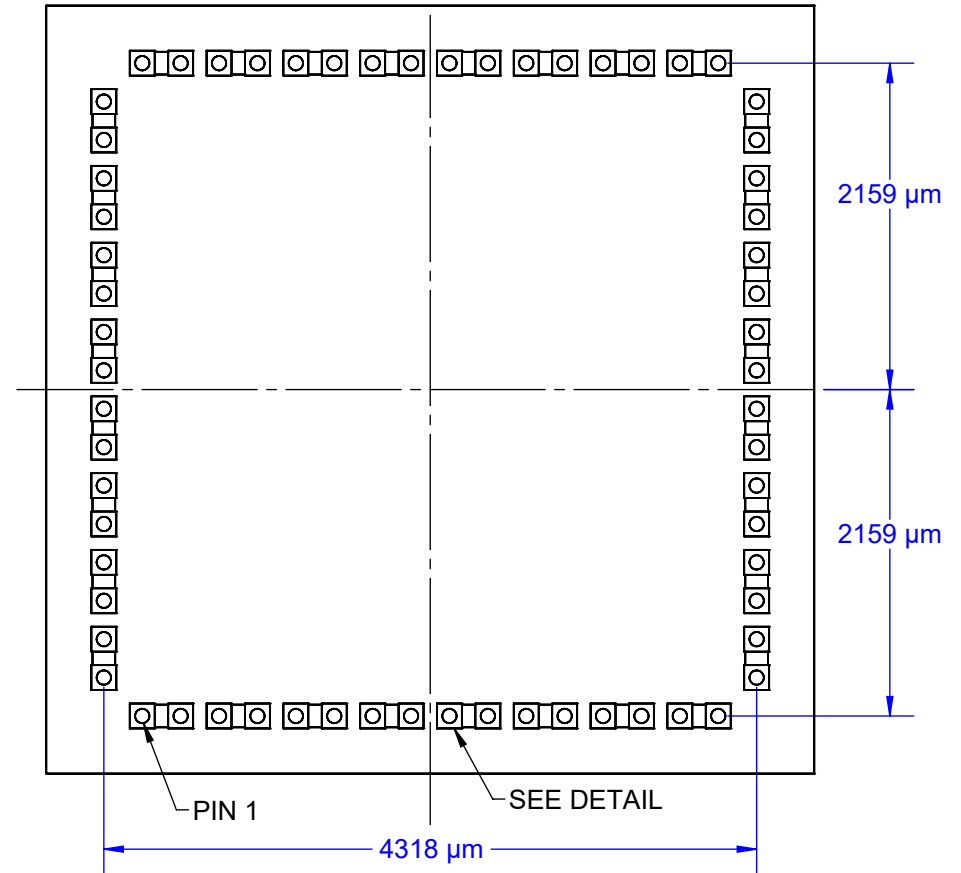
APPROVALS		DATE				
DRAWN	T. Au	04/16/25				
ENG	M. Hart	04/16/25	TITLE FCN64 - 254 μm PITCH			
MFG			DAISY CHAIN DIE			
QA			SCALE 15:1	SIZE A	DRAWING NO. 631610	REV A
CUST						
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 7

OUTLINE DIMENSIONS

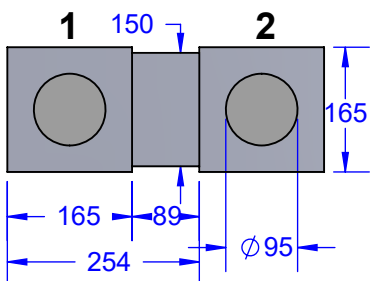
BACK SIDE



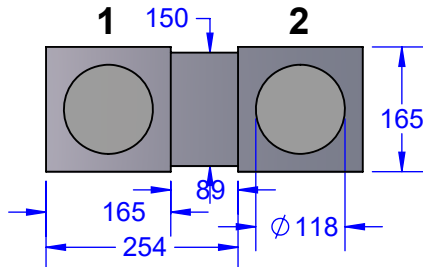
PAD SIDE



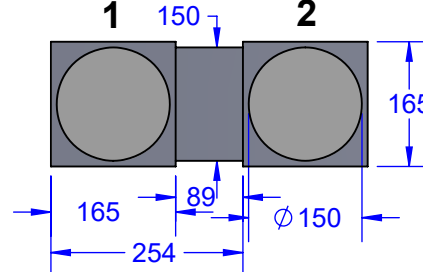
DETAIL 1



DETAIL 2



DETAIL 3



TopLine

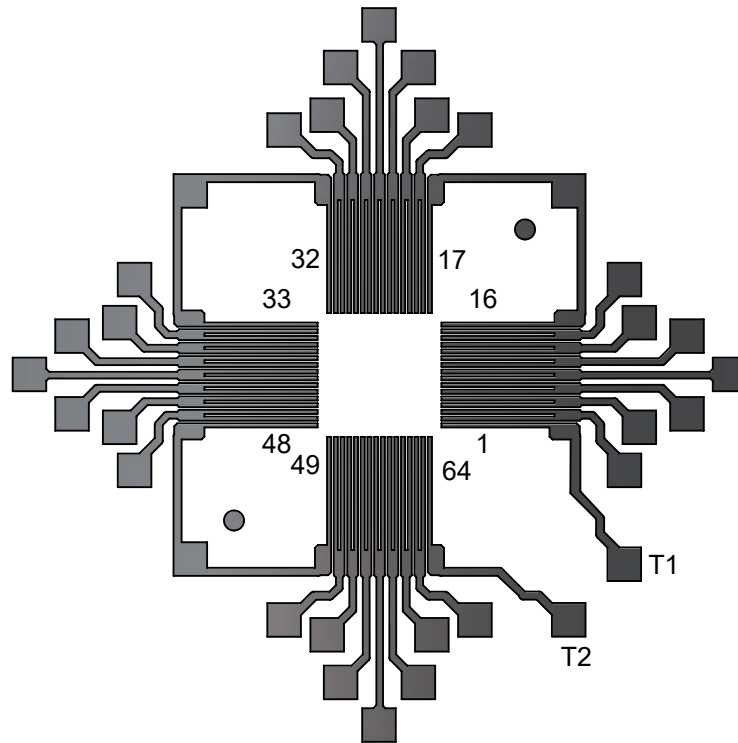
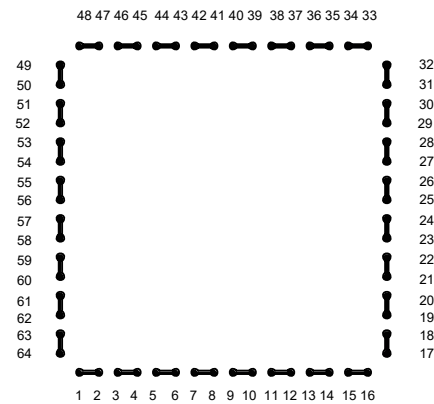
TITLE FCN64 - 254 μm PITCH
DAISY CHAIN DIE

SCALE 17.5:1	SIZE A	DRAWING NO. 631610	REV A
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DO NOT SCALE DRAWING

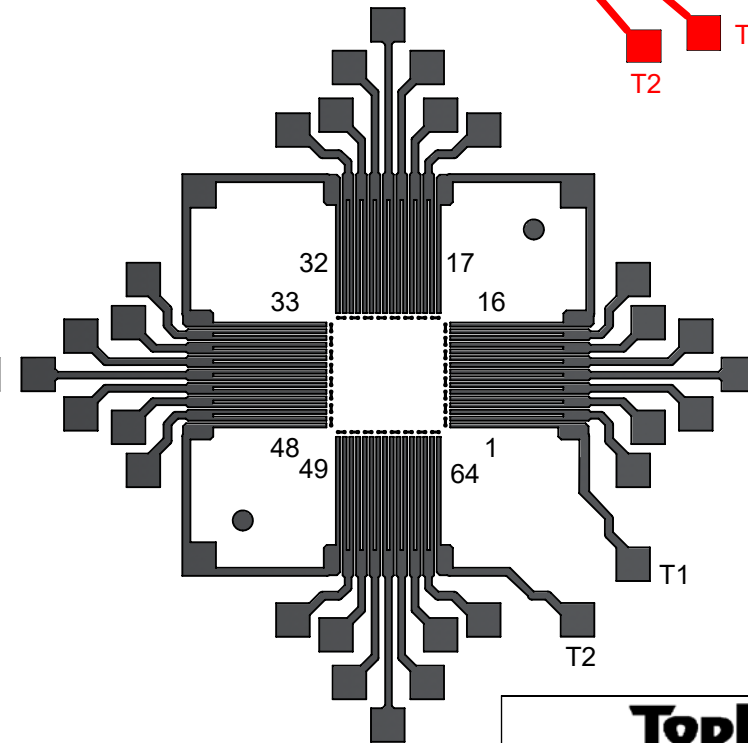
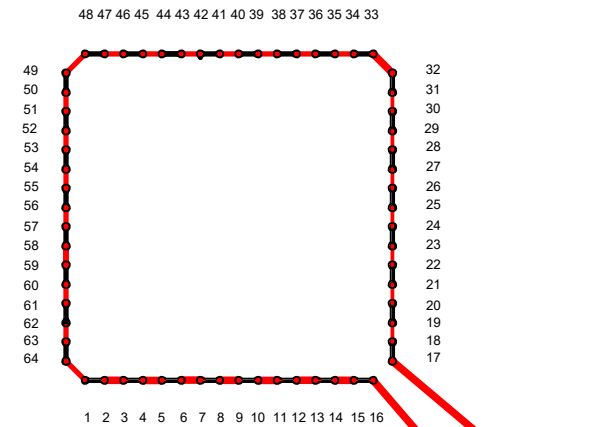
SHEET 2 OF 7

PAD VIEW



PCB VIEW
SCALE: 3.5/1

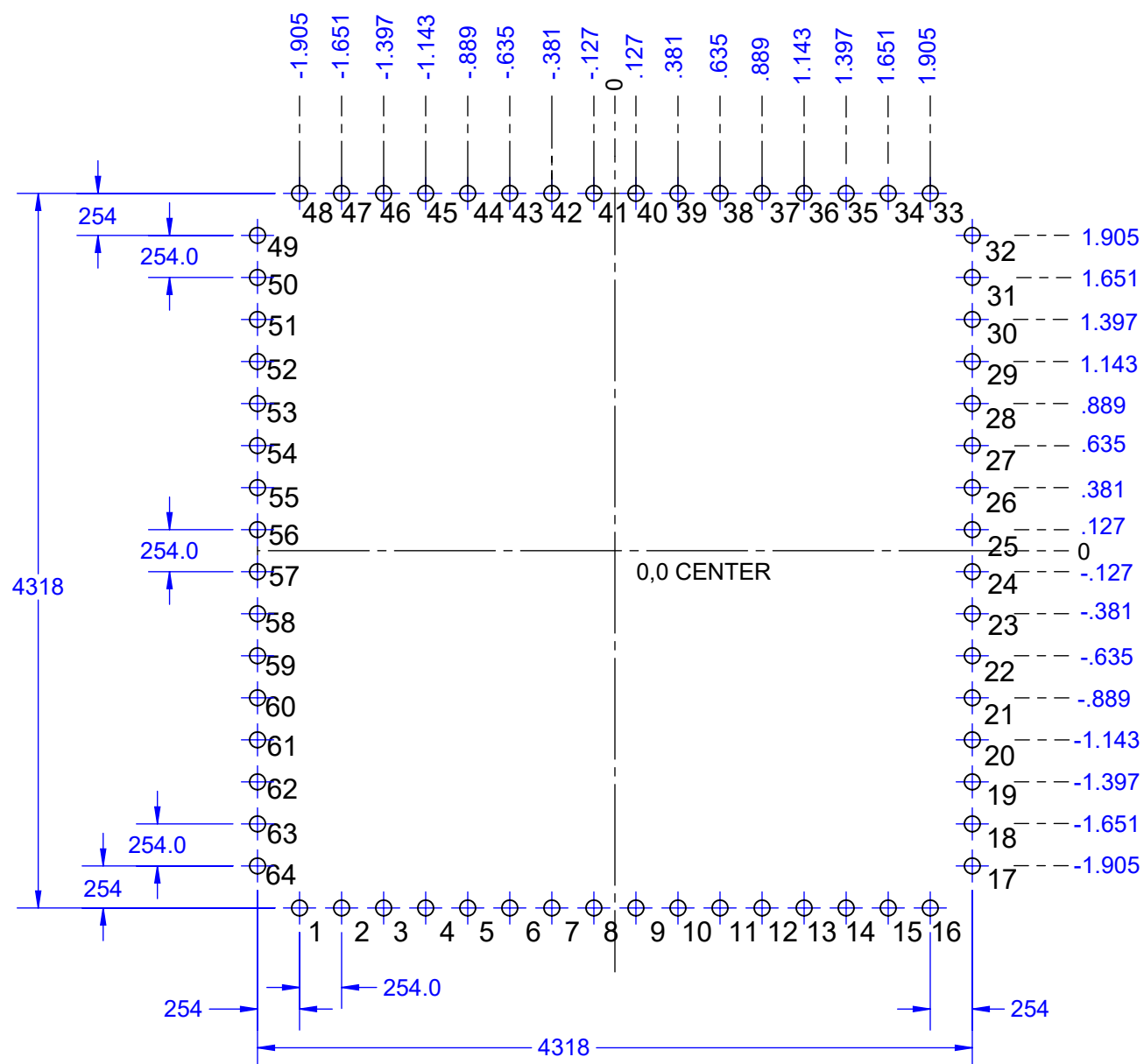
AFTER BONDING



AFTER BONDING
SCALE: 3.5/1

TopLine®			
TITLE FCN64 - 254um PITCH DAISY CHAIN DIE			
SCALE 10:1	SIZE A	DRAWING NO. 631610	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 7

**PAD LOCATION
DIMENSION MICRON (μm)**



NOTES:

- NOTES:
1) DIMENSIONS: MICRONS (μm).
2) X=0, Y=0 IS CENTER OF DIE.
3) SEE NET LIST PAGE 6.

TopLine®

TITLE	FCN64 - 254um PITCH DAISY CHAIN DIE
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SCALE
10:1

SIZE
A

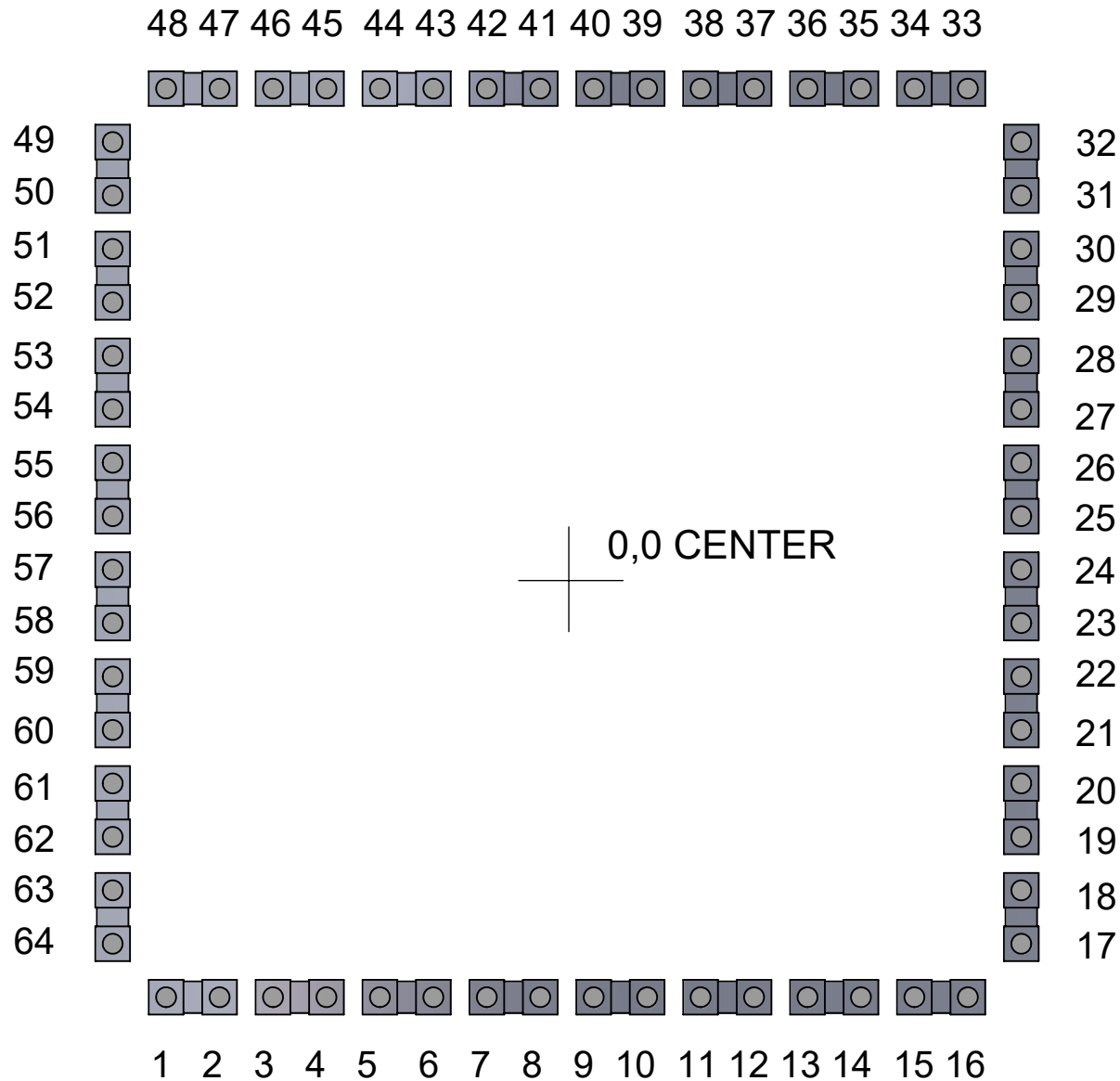
DRAWING NO.
631610

REV
A

DO NOT SCALE DRAWING

SHEET 4 OF 7

**BONDING MAP
SEE NET LIST (PAGE 6)**



TopLine[®]			
TITLE FCN64 - 254um PITCH DAISY CHAIN DIE			
SCALE 25:1	SIZE A	DRAWING NO. 631610	REV A
DO NOT SCALE DRAWING		SHEET 5 OF 7	

FCN64 NET LIST
MICRON (μm)
(0,0) LOCATED AT THE CENTER OF THE DIE

PIN#	X	Y
1	-1905	- 2159
2	-1651	- 2159
3	-1397	- 2159
4	-1143	- 2159
5	-889	- 2159
6	-635	- 2159
7	-381	- 2159
8	-127	- 2159
9	127	- 2159
10	381	- 2159
11	635	- 2159
12	889	- 2159
13	1143	- 2159
14	1397	- 2159
15	1651	- 2159
16	1905	- 2159
17	2159	-1905
18	2159	-1651
19	2159	-1397
20	2159	-1143
21	2159	-889
22	2159	-635

PIN#	X	Y
23	2159	-381
24	2159	-127
25	2159	127
26	2159	381
27	2159	635
28	2159	889
29	2159	1143
30	2159	1397
31	2159	1651
32	2159	1905
33	1905	2159
34	1651	2159
35	1397	2159
36	1143	2159
37	889	2159
38	635	2159
39	381	2159
40	127	2159
41	-127	2159
42	-381	2159
43	-635	2159
44	-889	2159

PIN#	X	Y
45	-1143	2159
46	-1397	2159
47	-1651	2159
48	-1905	2159
49	-2159	1905
50	-2159	1651
51	-2159	1397
52	-2159	1143
53	-2159	889
54	-2159	635
55	-2159	381
56	-2159	127
57	-2159	-127
58	-2159	-381
59	-2159	-635
60	-2159	-889
61	-2159	-1143
62	-2159	-1397
63	-2159	-1651
64	-2159	-1905

NOTES:

- 1) DIMENSIONS: MICRON (μm).
- 2) X = 0, Y = 0 IS CENTER OF DIE.

TopLine®			
TITLE FCN64 - 254μm PITCH DAISY CHAIN DIE			
SCALE 10:1	SIZE A	DRAWING NO. 631610	REV A
DO NOT SCALE DRAWING			SHEET 6 OF 7

PART NUMBERING SYSTEM

FCN

64

K

5

A

254

- OPTION

- DC

- PACKING

BONDING DIE

FCN = SINGLE DIE
FCWN = UNSAWN WAFER
5" (125mm)

NBR BOND PADS

PADS	DIE ARRAY	SIZE
64	1X	5mm
128	4X	10mm
192	9X	15mm
256	16X	20mm

PAD

K = ϕ 95 μ m
N = ϕ 118 μ m
U = ϕ 150 μ m

DIE SIZE

CODE	MM	MIL
5	5.08	200
10	10.16	400
15	15.24	600
20	20.32	800

PAD MATERIAL

A = Al98, Si1.0 Cu1.0

BUMP PITCH

μ m

OPTIONS

DIE THINNING		
CODE	μ M	INCH
NONE	635 μ m	.025"
BG530	530 μ m	.021"
BG430	430 μ m	.017"
BG360	360 μ m	.014"
BG250	250 μ m	.010"
BG200	200 μ m	.008"
BG150	150 μ m	.006"
BG100	100 μ m	.004"

OTHER THICKNESS AVAILABLE

DAISY CHAIN

PACKAGING

BLANK = TRAY (STANDARD)

SIZE	TRAY	QTY
5MM	2-INCH	36 PCS
10MM	4-INCH	49 PCS
15MM	4-INCH	25 PCS
20MM	4-INCH	9 PCS

TopLine®

TITLE FCN64 - 254 μ m PITCH
DAISY CHAIN DIE

SCALE	SIZE	DRAWING NO.	REV
10:1	A	631610	A

DO NOT SCALE DRAWING

SHEET 7 OF 7